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November 2014

## FFH60UP40S, FFH60UP40S3 60 A, 400 V, Ultrafast Diode

### Features

- Ultrafast Recovery,  $T_{rr} = 85$  ns (@  $I_F = 60$  A)
- Max Forward Voltage,  $V_F = 1.3$  V (@  $T_C = 25^\circ\text{C}$ )
- Avalanche Energy Rated
- RoHS compliant

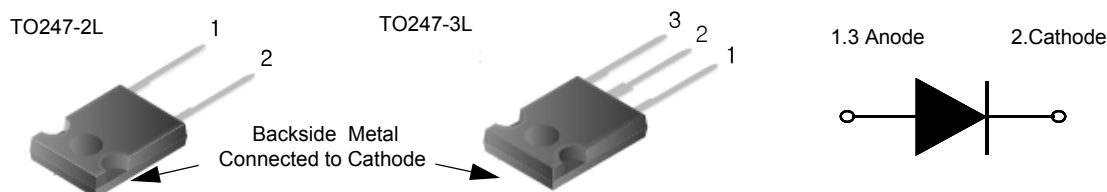
### Applications

- General Purpose
- SMPS, Welder, UPS
- Free-wheeling Diode for motor application
- Power switching circuits

### Description

The FFH60UP40S, FFH60UP40S3 is an ultrafast diode with low forward voltage drop and rugged UIS capability. This device is intended for use as freewheeling and clamping diodes in a variety of switching power supplies and other power switching applications. It is specially suited for use in switching power supplies and industrial applications as welder and UPS application.

### Pin Assignments



### Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Unit
$V_{RRM}$	Peak Repetitive Reverse Voltage	400	V
$V_{RWM}$	Working Peak Reverse Voltage	400	V
$V_R$	DC Blocking Voltage	400	V
$I_{F(AV)}$	Average Rectified Forward Current @ $T_C = 139^\circ\text{C}$	60	A
$I_{FSM}$	Non-repetitive Peak Surge Current 60Hz Single Half-Sine Wave	600	A
$T_J, T_{STG}$	Operating and Storage Temperature Range	-65 to +150	$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JC}$	Maximum Thermal Resistance, Junction to Case	0.2	$^\circ\text{C/W}$

### Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FFH60UP40S	FFH60UP40S	TO247-2L	Tube	N/A	N/A	30
FFH60UP40S3	FFH60UP40S3	TO247-3L	Tube	N/A	N/A	30

## Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter		Min.	Typ.	Max.	Unit
$V_F1$	$I_F = 60\text{ A}$	$T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$	-	1.06 0.99	1.3 -	V
$I_{R1}$	$V_R = 400\text{ V}$	$T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$	-	-	100 500	$\mu\text{A}$
$t_{rr}$	$I_F = 60\text{ A}$ , $di_F/dt = 200\text{ A}/\mu\text{s}$ , $V_R = 260\text{ V}$	$T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$	-	59 96	85 -	ns
$W_{AVL}$	Avalanche Energy ( $L = 40\text{ mH}$ )		50	-	-	mJ

### Notes:

1: Pulse: Test Pulse width =  $300\mu\text{s}$ , Duty Cycle = 2%

## Test Circuit and Waveform

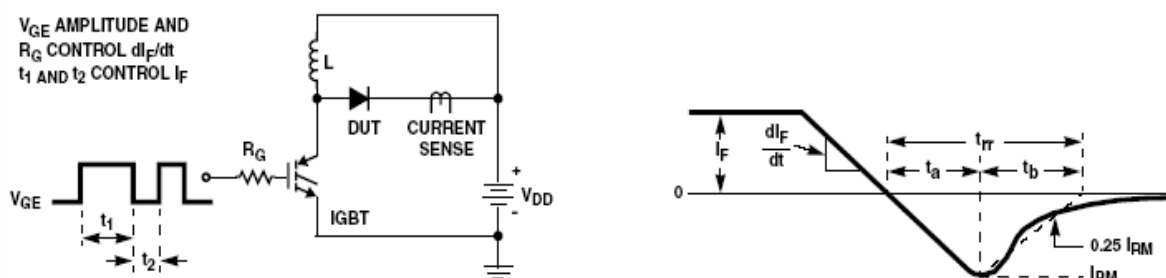


Figure 1. Diode Reverse Recovery Test Circuit & Waveform

$L = 40\text{mH}$   
 $R < 0.1\Omega$   
 $V_{DD} = 50\text{V}$

$E_{AVL} = 1/2LI^2 [V_{R(AVL)}/(V_{R(AVL)} - V_{DD})]$   
 $Q1 = \text{IGBT (}BV_{CES} > V_{R(AVL)}\text{)}$

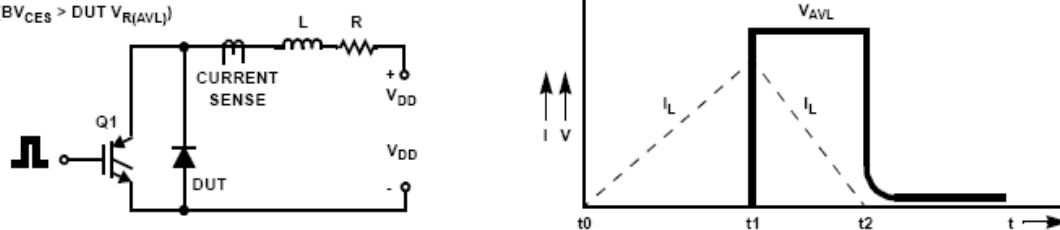
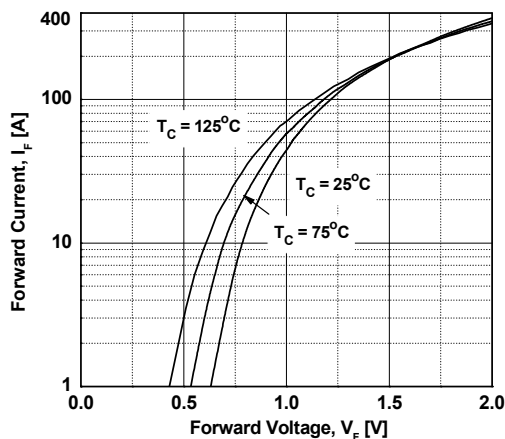


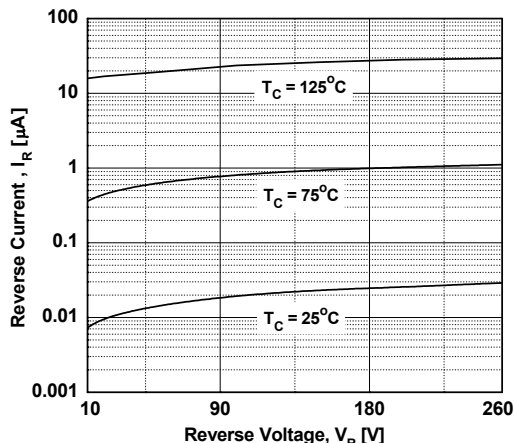
Figure 2. Unclamped Inductive Switching Test Circuit & Waveform

## Typical Performance Characteristics

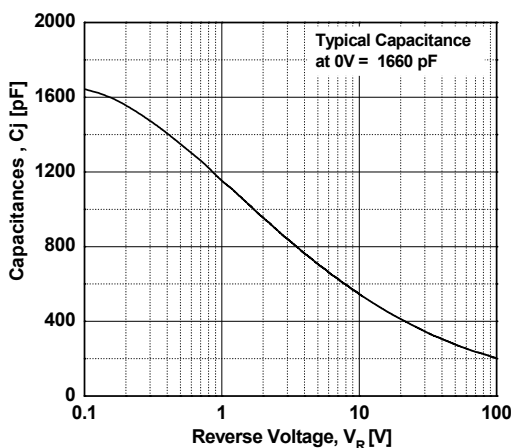
**Figure 3. Typical Forward Voltage Drop vs. Forward Current**



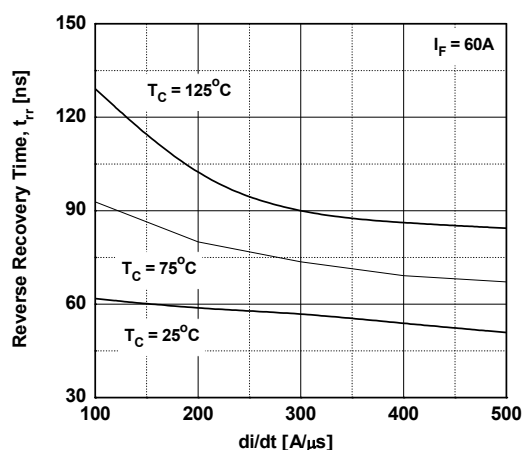
**Figure 4. Typical Reverse Current vs. Reverse Voltage**



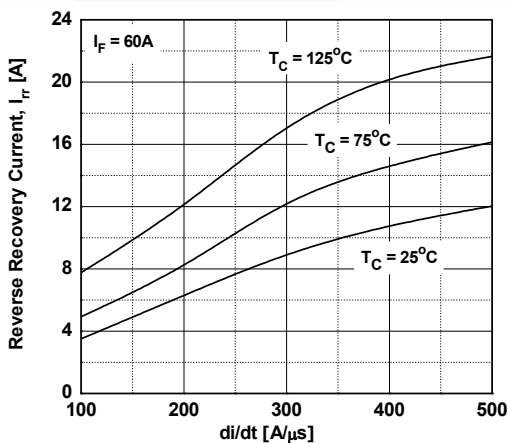
**Figure 5. Typical Junction Capacitance**



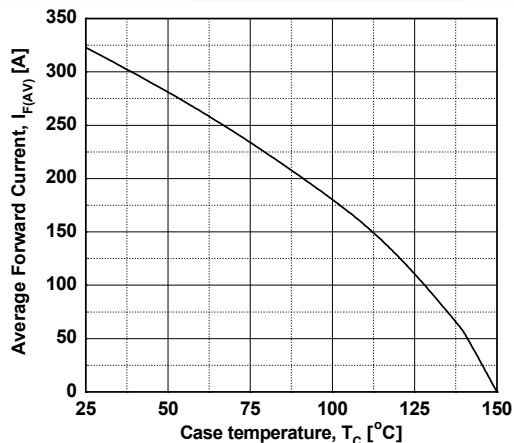
**Figure 6. Typical Reverse Recovery Time vs. di/dt**



**Figure 7. Typical Reverse Recovery Current vs. di/dt**

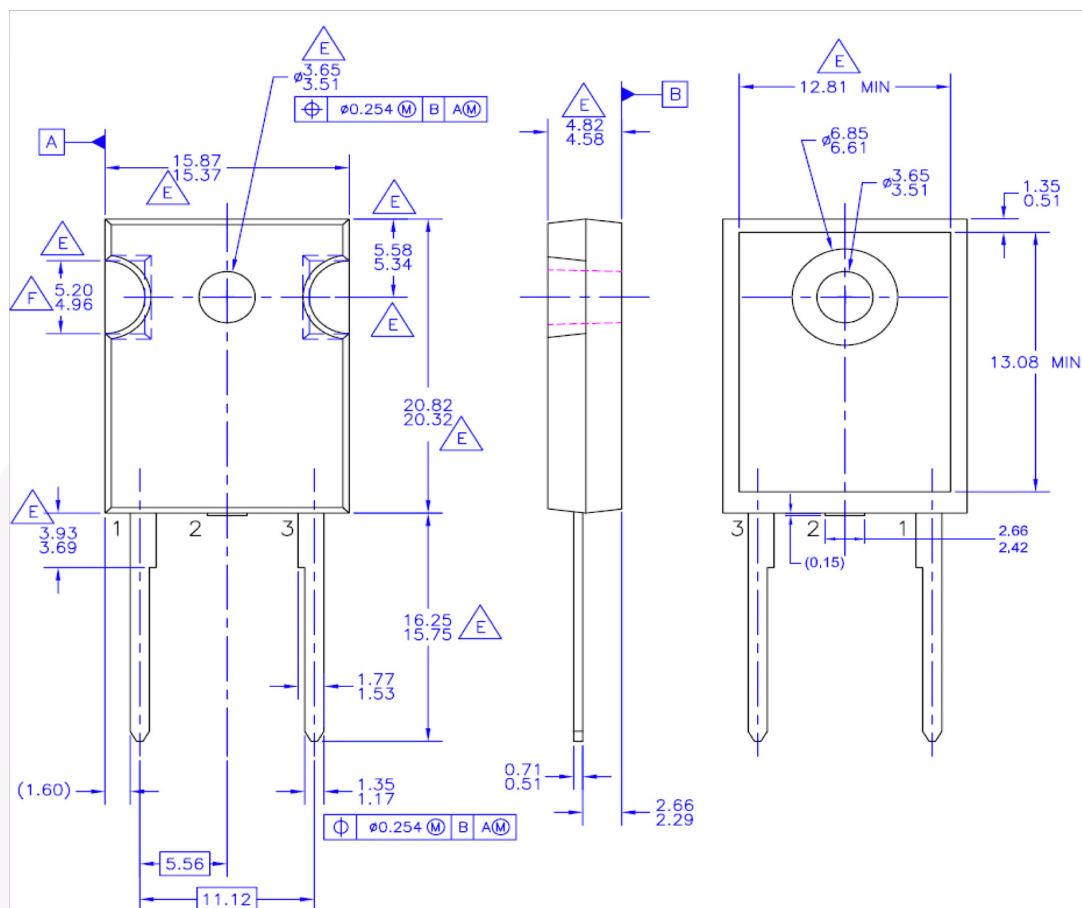


**Figure 8. Forward Current Derating Curve**



## Mechanical Dimensions

### TO247-2L



#### NOTES: UNLESS OTHERWISE SPECIFIED

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**F.** NOTCH MAY BE SQUARE

**G.** DRAWING FILENAME: MKT-TO247B02\_REV02

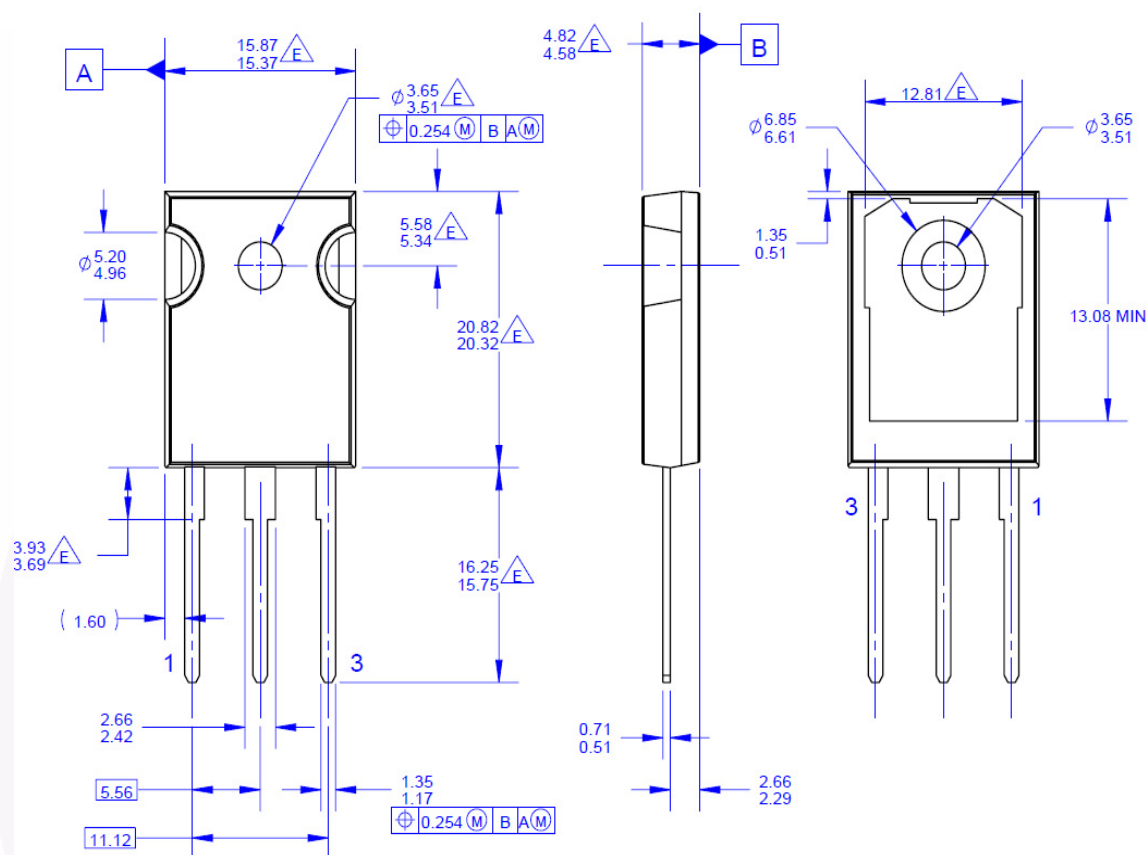
**Figure 9. TO-247, Molded, 2LD, Jedec Option AB**

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TO247-3L



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**Figure 10. TO-247,Molded, 3LD, Jedec Option AB**

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